

Amendment To The Claims

This listing will replace all prior versions and listings of the claims in this application.

Listing of Claims

1. (Currently amended) A method of making a segmented composition comprising the steps of:

~~thermally transferring heat from a first molten component to a second cool liquefied or dispersed component; and~~

~~thermally transferring coolness from said second component to said first component,~~

~~whereby the thermal transfer of heat and coolness virtually simultaneously solidifies said first component and said second component into first and second discrete segments, respectively, of the composition~~

providing a molten first component at a first temperature and in a liquefied or dispersed state, the first component being in such state above its liquefying/dispersing temperature and being solidified at or below such temperature;

providing a cool second component at a second temperature that is lower than the first temperature and in a liquefied or dispersed state, the second component being in such state below its liquefying/dispersing temperature and being solidified at or above such temperature, the second component being in segmented juxtaposition relative to the first component;

allowing heat to transfer from the first component to the second component, and

allowing the first component and the second component to reach room temperature,

whereby heat removed from the first component solidifies the first component, and heat added to the second component solidifies the second component, thereby forming first and second discrete segments of the segmented composition.

2. (Original) The method of claim 1, wherein said first component becomes liquefied or dispersed at a temperature about 50°C or greater.

3. (Original) The method of claim 2, wherein said second component becomes liquefied or dispersed at a temperature about 15°C or less.

4. (Original) The method of claim 1, wherein said first component has a wax base.

5. (Original) The method of claim 4, wherein said wax base is a natural or synthetic wax.

6. (Original) The method of claim 4, wherein said wax base is one or more hard waxes having C₈ to C₅₀ hydrocarbons.

7. (Original) The method of claim 4, wherein said wax base is a wax selected from the group consisting of: carnauba, ozokerite, candelilla, paraffin, ceresin, lanolin, beeswax, polyethylene, microcrystalline wax, and any combination thereof.

8. (Original) The method of claim 1, wherein said second component is wax-free.

9. (Original) The method of claim 8, wherein said second component is a smectite clay dispersed in a solvent.

10. (Original) The method of claim 9, wherein said solvent is an organic solvent.

11. (Original) The method of claim 10, wherein said organic solvent is selected from the group consisting of one or more: acetates, alcohols, aliphatic hydrocarbons, aromatic hydrocarbons, ethers, formamides, halogenated hydrocarbons, phenyl di- and tri- methicones, ketones, methacrylates, phthalates, sulfoxides, and any mixtures thereof.

12. (Original) The method of claim 10, wherein said smectite clay is present in an amount about 10 wt% to about 50 wt% and said organic solvent is present in an amount about 50 wt% to about 90 wt%, based on the total weight of the second component.

13. (Original) The method of claim 3, wherein said first and said second components have a liquefying/dispersing temperature difference of at least 10°C to about 85°C.

14. (Original) The method of claim 13, wherein the temperature difference is about 30°C to about 50°C.

15. (Original) The method of claim 1, further comprising adding to said second component a heat sensitive active ingredient in an active effective amount.

16. (Original) The method of claim 15, wherein the active ingredient is selected from the group consisting of bioflavonoids, botanicals, fragrances, silicones, yeast, pheromones, collagen, ascorbyl phosphoryl, cholesterol, vitamins A, B1, B2, B12, C and D3, any derivatives thereof and any mixtures thereof.

17. (Original) The method of claim 1, wherein the composition is selected from the group consisting of a lipstick, pomade, lip gloss, eyeshadow, concealer, moisturizer, skin care product, deodorant, and foundation.

18. (Withdrawn) A method of making a composition comprising the steps of:

heating a first component having a liquefying/dispersing temperature of about 50°C or greater to a liquefied/dispersed state;

cooling a second component having a liquefying/dispersing temperature of less than about 15°C to a liquefied/dispersed state;

placing the heated, liquefied/dispersed first component into a molding apparatus;

placing the cooled, liquefied/dispersed second component into said molding apparatus;

thermally transferring heat and coolness between said first component and said second components;

at least partially setting up said first component as a result of thermal exposure to the coolness of said second component; and

simultaneously at least partially setting up said second component as a result of thermal exposure to the heat of said first component.

19. (Withdrawn) The method of claim 18, wherein the liquefying/dispersing temperature of said first component is greater than about 60°C and the liquefying/dispersing temperature of said second component is less than about 15°C.

20. (Withdrawn) The method of claim 18, wherein said first and said second components have a liquefying/dispersing temperature difference of at least 10°C to about 85°C.

21. (Withdrawn) The method of claim 20, wherein the temperature difference is about 30°C to about 50°C.

22. (Withdrawn) The method of claim 18, wherein the liquefied/dispersed first component is placed into said molding apparatus at a temperature from about 70°C to about 90°C.

23. (Withdrawn) The method of claim 22, wherein the liquefied/dispersed second component is placed into said molding apparatus at a temperature from about -4°C to about 13°C.

24. (Withdrawn) The method of claim 18, wherein said first and said second components form discrete first and second segments of the composition upon being fully set-up.

25. (Withdrawn) The method of claim 18, further comprising blending said first and said second components before said first and said second components are fully set to create a marbleized composition.

26. (Withdrawn) The method of claim 18, wherein said first component has a wax base.

27. (Withdrawn) The method of claim 26, wherein said second component is wax-free.

28. (Withdrawn) The method of claim 27, wherein said second component is a smectite clay dispersed in a solvent.

29. (Withdrawn) The method of claim 24, wherein said molding apparatus forms said first and said second components in a core-sheath arrangement.

30. (Withdrawn) The method of claim 24, comprising

(a) inserting a hollow injector having a dispensing nozzle into a cavity of said molding apparatus;

(b) placing one of said first and said second components into said cavity to form a sheath at least partially about said injector;

(c) withdrawing said injector from said cavity to form a cavity core;

(d) dispensing the other of said first and said second components from said dispensing nozzle into said cavity core as said injector is withdrawn; and

(e) effecting said thermal exposure between said first and said second components.

31. (Withdrawn) The method of claim 24, comprising

(a) inserting a rod into a cavity of said molding apparatus;
(b) placing one of said first and said second components into said cavity to form a sheath at least partially about said rod;

(c) withdrawing said rod from said cavity to form a cavity core;

(d) placing the other of said first and said second components into said cavity core; and

(e) effecting said thermal exposure between said first and said second components.

32. (Withdrawn) The method of claim 24, comprising

(a) placing a solid hollow insert made of said first or said second component into a cavity of said molding apparatus;

(b) placing the other of said first and said second components different from said hollow insert into said cavity to form a sheath at least partially about said hollow insert;

(c) placing the other of said first and said second components into said hollow insert;

(d) at least partially liquefying or dispersing said hollow insert upon contact with said other of said first and said second components; and

(e) effecting said thermal exposure between said first and said second components.

33. (Withdrawn) The method of claim 24, comprising

(a) placing a perforated, hollow insert made of said first or said second component into a cavity of said molding apparatus;

(b) placing one of said first and said second components different from said hollow insert into said cavity to form a sheath at least partially about said hollow insert;

(c) placing the other of said first and said second components into said hollow insert;

(d) effecting said thermal exposure between said first and said second components.

34. (Withdrawn) The method of claim 24, comprising

(a) placing a solid hollow insert made of said first or said second component into a cavity of said molding apparatus;

(b) placing the other of said first and said second components different from said hollow insert into said cavity to form a sheath at least partially about said hollow insert;

(c) placing the other of said first and said second components into said hollow insert;

(d) at least partially sublimating said hollow insert upon contact with said other of said first and said second components; and

(e) effecting said thermal exposure between said first and said second components.

35. (Currently amended) A composition comprising a first component having a liquefying or dispersing temperature of about 50°C or greater, the first component solidifying at a temperature at or below its liquefying/dispersing temperature, and a second component having a liquefying or dispersing temperature less than about 15°C, the second component solidifying at or above its liquefying/dispersing temperature, wherein said first and said second components are in contact with each other, and one of said first and said second components is adjacent to, partially surrounded by or fully surrounded by the other of said first and said second components, and wherein said first and said second components form two discrete segments of the composition at room temperature.

36. (Original) The composition of claim 35, wherein said first component is wax-based, and wherein said second component is wax-free.

37. (Original) The composition of claim 35, wherein said second component comprises a smectite clay.

38. (Currently amended) A composition comprising:

a molten first ~~molten~~ component having a first temperature that is above the temperature at which it liquefies or disperses;
and

a ~~second~~ liquefied or dispersed second component segmentedly juxtaposed to said first component, said second component ~~including~~ comprising a smectite clay and having a second temperature that is lower than said first temperature and lower than its liquefying/dispersing temperature, the second component solidifying at a temperature at or above its liquefying/dispersing temperature,

wherein heat is ~~thermally transferred~~ transferable from said first component to said second component ~~and coolness is thermally transferred from said second component to said first component,~~ and wherein said first and said second components form two discrete segments of the composition at room temperature.

39. (Original) The composition of claim 38, wherein said first temperature is about 70°C to about 80°C and said second temperature is about -4°C to about 13°C.

40. (Withdrawn) An injection molding apparatus for making a segmented composition comprising:

a cavity;

a hollow injector having a dispensing nozzle that is adapted to be positioned in said cavity,

means for placing a molten component of the composition into said cavity as a sheath at least partially about said injector;

means for withdrawing said injector from said cavity thereby forming a core cavity,

whereby a cold component of the composition is dispensed through said injector and discharged through said dispensing nozzle into said core cavity,

wherein the cold component fully fills said core cavity and a thermal exchange between the molten and cold components rapidly accelerates the formation of the composition when said injector is fully withdrawn.

41. (Currently amended) The method of claim 1, further comprising the steps of ~~wherein~~ liquefying or dispersing said first component and said second component ~~are liquefied or dispersed and are placed~~ placing said components into an injection molding apparatus ~~to thermally transfer heat and coolness between~~ in which heat transfers from said first component ~~and to~~ to said second component.

42. (Previously presented) The method of claim 41, wherein the liquefying/dispersing temperature of said first component is greater than about 60°C, and wherein the liquefying/dispersing temperature of said second component is less than about 15°C.

43. (Previously presented) The method of claim 41, wherein said first and said second components have a liquefying/dispersing temperature difference of at least about 10°C to about 85°C.

44. (Previously presented) The method of claim 43, wherein the temperature difference is about 30°C to about 50°C.

45. (Previously presented) The method of claim 41, wherein the liquefied/dispersed first component is placed into said molding apparatus at a temperature from about 70°C to about 90°C.

46. (Previously presented) The method of claim 45, wherein the liquefied/dispersed second component is placed into said molding apparatus at a temperature from about -4°C to about 13°C.

47. (Previously presented) The method of claim 41, wherein said first and said second components form discrete first and second segments of the composition upon being fully set-up.

48. (Previously presented) The method of claim 41, further comprising blending said first and said second components before said first and said second components are fully set to create a marbleized composition.

49. (Previously presented) The method of claim 41, wherein said first component has a wax base.

50. (Previously presented) The method of claim 49, wherein said second component is wax-free.

51. (Previously presented) The method of claim 50, wherein said second component is a smectite clay dispersed in a solvent.

52. (Previously presented) The method of claim 47, wherein said molding apparatus forms said first and said second components in a core-sheath arrangement.

53. (Currently amended) The method of claim 47, further comprising the steps of

(a) inserting a hollow injector having a dispensing nozzle into a cavity of said molding apparatus;

(b) placing one of said first and said second components into said cavity to form a sheath at least partially about said injector;

(c) withdrawing said injector from said cavity to form a cavity core; and

(d) dispensing the other of said first and said second components from said dispensing nozzle into said cavity core as said injector is withdrawn; ~~and~~

~~(e) effecting said thermal exposure between said first and said second components.~~

54. (Currently amended) The method of claim 47, further comprising the steps of

(a) inserting a rod into a cavity of said molding apparatus;

(b) placing one of said first and said second components into said cavity to form a sheath at least partially about said rod;

(c) withdrawing said rod from said cavity to form a cavity core; and

(d) placing the other of said first and said second components into said cavity core; ~~and~~

~~(e) effecting said thermal exposure between said first and said second components.~~

55. (Currently amended) The method of claim 47, further comprising the steps of

(a) placing a solid hollow insert made of said first or said second component into a cavity of said molding apparatus;

(b) placing the other of said first and said second components different from said hollow insert into said cavity to form a sheath at least partially about said hollow insert;

(c) placing the other of said first and said second components into said hollow insert; and

(d) at least partially liquefying or dispersing said hollow insert upon contact with said other of said first and said second components; ~~and~~

~~(e) effecting said thermal exposure between said first and said second components.~~

56. (Currently amended) The method of claim 47, further comprising the steps of

(a) placing a perforated, hollow insert made of said first or said second component into a cavity of said molding apparatus;

(b) placing one of said first and said second components different from said hollow insert into said cavity to form a sheath at least partially about said hollow insert; and

(c) placing the other of said first and said second components into said hollow insert; ~~and~~

~~(d) effecting said thermal exposure between said first and said second components.~~

57. (Currently amended) The method of claim 47, further comprising the steps of

(a) placing a solid hollow insert made of said first or said second component into a cavity of said molding apparatus;

(b) placing the other of said first and said second components different from said hollow insert into said cavity to form a sheath at least partially about said hollow insert;

(c) placing the other of said first and said second components into said hollow insert; and

(d) at least partially sublimating said hollow insert upon contact with said other of said first and said second components; ~~and~~

~~(e) effecting said thermal exposure between said first and said second components.~~

58. (Currently amended) The composition of claim 35, wherein the liquefying/dispersing temperature of said first component is greater than about 60°C, and wherein the liquefying/dispersing temperature of said second component is less than about ~~15°C~~ 13°C.

59. (Previously presented) The composition of claim 35, wherein said first and said second components have a liquefying/dispersing temperature difference of at least about 10°C to about 85°C.

60. (Previously presented) The composition of claim 59, wherein the temperature difference is about 30°C to about 50°C.

61. (Previously presented) The composition of claim 35, wherein the first component is liquefied or dispersed and is placed into a molding apparatus at a temperature from about 70°C to about 90°C.

62. (Previously presented) The composition of claim 61, wherein the second component is liquefied or dispersed and is placed into said molding apparatus at a temperature from about -4°C to about 13°C.

63. (Previously presented) The composition of claim 35, wherein said first and said second components form discrete first and second segments of the composition upon being fully set-up.

64. (Previously presented) The composition of claim 35, wherein the composition is marbled.

65. (Previously presented) The composition of claim 35, wherein said first component has a wax base.

66. (Previously presented) The composition of claim 65, wherein said second component is wax-free.

67. (Previously presented) The composition of claim 66, wherein said second component is a smectite clay dispersed in a solvent.

68. (New) The composition of claim 67, wherein the smectite clay dispersion sets up at or above its liquefying/dispersing temperature.

69. (New) The composition of claim 38, wherein the smectite clay is dispersed in a solvent, the dispersion being capable of setting up when the temperature is above the second temperature.

70. (New) The method of claim 10, wherein the smectite clay dispersion sets up when the temperature of the second component is above its liquefying/dispersing temperature.

71. (New) The composition made by the process of Claim 1.

72. (New) The composition made by the process of Claim 70.